12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20261105000.1	PCN Issued	November 06, 2026
Qualification of LFAB as an additional Wafer Fab site for select devices		Sample request deadline:	January 05, 2027
		Estimated 1st ship date:	February 04, 2027
***Sample requests received after** January 05, 2027* **will not be supported.**			

Change type(s)
Packing/Shipping/Labeling Wafer Fab Site

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of LFAB as an additional Wafer Fab site for the products listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process Technology	Wafer Diameter	Additional Fab site	Process Technology	Wafer Diameter
UMC	F65	300mm	**LFAB**	F65	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• Request the Supporting Data Packet for more details on the changes.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMC	UMI	SGP	SUNNYVALE
LFAB	**LHI**	**USA**	**Lehi**

	Sample product shipping label (not actual product label): 

Products Affected

CC1312PSIPMOTR			

Approve Date 3-November-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC1312PSIPMOTR	QBS Package Reference: CC2652PSIPMOTR	QBS Process Reference: CC2642R1FRGZR
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	-	3/78/0	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	1/77/0	3/231/0	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	1/77/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	1/22/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device CC1312PSIPMOTR is qualified at MSL3 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2409-020

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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